

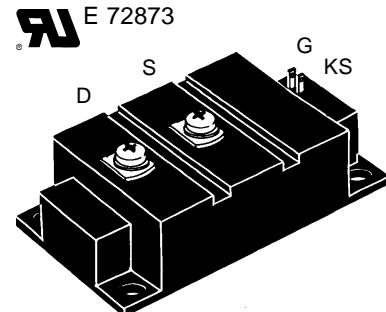
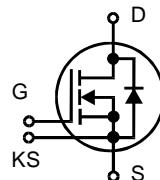
HiPerFET™ MOSFET Module

VMO 550-01F

V_{DSS} = 100 V
 I_{D25} = 590 A
 $R_{DS(on)}$ = 2.1 mΩ

N-Channel Enhancement Mode

Preliminary Data



D = Drain S = Source
 KS = Kelvin Source G = Gate

Symbol	Test Conditions	Maximum Ratings		
V_{DSS}	T_J = 25°C to 150°C	100		V
V_{DGR}	T_J = 25°C to 150°C; R_{GS} = 10 kΩ	100		V
V_{GS}	Continuous	±20		V
V_{GSM}	Transient	±30		V
I_{D25}	T_S = 25°C	590		A
I_{D80}	T_S = 80°C	440		A
I_{DM}	T_S = 25°C	pulse width limited by T_{JM}		2360 A
P_D	T_c = 25°C	2200		W
	T_s = 25°C	1470		W
T_J		-40 ... +150		°C
T_{JM}		150		°C
T_{stg}		-40 ... +125		°C
V_{ISOL}	50/60 Hz	3000		V~
	$I_{ISOL} \leq 1$ mA	3600		
M_d	Mounting torque (M6) Terminal connection torque (M5)	2.25-2.75/20-25 2.5-3.7/22-33	Nm/lb.in.	Nm/lb.in.
Weight	typical including screws	250		g

Symbol	Test Conditions	Characteristic Values		
		(T_J = 25°C, unless otherwise specified)	min.	typ.
V_{DSS}	$V_{GS} = 0$ V, $I_D = 6$ mA	100		V
$V_{GS(th)}$	$V_{DS} = 20$ V, $I_D = 110$ mA	3		6 V
I_{GSS}	$V_{GS} = \pm 20$ V DC, $V_{DS} = 0$		±500	nA
I_{DSS}	$V_{DS} = 0.8 \cdot V_{DSS}$ $V_{GS} = 0$ V	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	3 mA 12 mA	
$R_{DS(on)}$	$V_{GS} = 10$ V, $I_D = 0.5 \cdot I_{D25}$ Pulse test, $t \leq 300$ µs, duty cycle $d \leq 2\%$		2.1	mΩ

IXYS reserves the right to change limits, test conditions and dimensions.

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Features

- International standard package
- Direct Copper Bonded Al_2O_3 ceramic base plate
- Isolation voltage 3600 V~
- Low $R_{DS(on)}$ HDMOS™ process
- Low package inductance for high speed switching
- Kelvin Source contact for easy drive

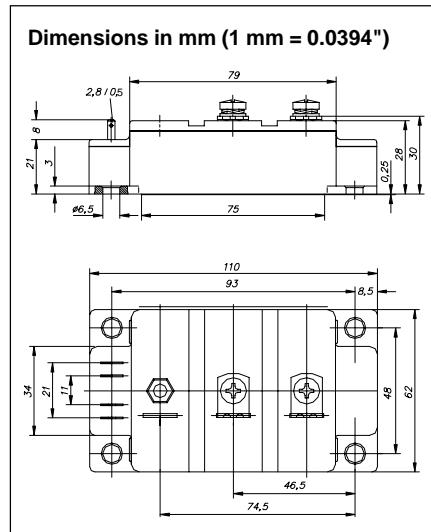
Applications

- AC motor speed control for electric vehicles
- DC servo and robot drives
- Switched-mode and resonant-mode power supplies
- DC choppers

Advantages

- Easy to mount
- Space and weight savings
- High power density
- Low losses

Symbol	Test Conditions	Characteristic Values		
		$(T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
g_{fs}	$V_{DS} = 10 \text{ V}; I_D = 0.5 \cdot I_{D25}$ pulsed	330	S	
C_{iss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	50	nF	
C_{oss}		17.6	nF	
C_{rss}		8.8	nF	
$t_{d(on)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 2 \Omega$ (external)	250	ns	
t_r		500	ns	
$t_{d(off)}$		800	ns	
t_f		200	ns	
Q_g	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$	2000	nC	
Q_{gs}		385	nC	
Q_{gd}		940	nC	
R_{thJC}			0.057 K/W	
R_{thJS}	with 30 μm heat transfer paste		0.085 K/W	



Symbol	Test Conditions	Characteristic Values		
		$(T_J = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
I_s	$V_{GS} = 0 \text{ V}$		590	A
I_{SM}	Repetitive; pulse width limited by T_{JM}		2360	A
V_{SD}	$I_F = I_s; V_{GS} = 0 \text{ V}$, Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $d \leq 2 \%$	0.9	1.2	V
t_{rr}	$I_F = I_s, -di/dt = 1000 \text{ A}/\mu\text{s}, V_{DS} = 0.5 \cdot V_{DSS}$	300		ns